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Rev. A2

SMB1N-1200S

• Infrared High Power LED

• 1200 nm, 50 mW

• SMD package, PA9T

• Dimension: 5.0 x 5.2 x 1.0 mm

• Viewing Angle: 136°





Description

SMB1N-1200S is a surface mount InGaAsP High Power LED with a typical peak wavelength of **1200 nm** and radiation of **50 mW**. It comes in SMD package (PA9T) with silver plated soldering pads (lead free solderable), copper heat sink, and molded with silicone resin.

Maximum Ratings (TCASE=25°C)

B	Complete I	Val	11.24		
Parameter	Symbol	Min.	Max.	Unit	
Power Dissipation	P_D		840	mW	
Forward Current	IF		600	mA	
Pulse Forward Current *1	I _{FP}		2000	mA	
Reverse Voltage	V_R		5	V	
Thermal Resistance	R_{THJA}		10	K/W	
Junction Temperature	T_J		120	°C	
Operating Temperature	T_{CASE}	- 40	+ 100	°C	
Storage Temperature	T_{STG}	- 40	+ 100	°C	
Lead Solder Temperature *2	T_{SLD}		+ 250	°C	

^{*1} duty=1%, pulse width = 10 µs

Electro-Optical Characteristics (TCASE=25°C)

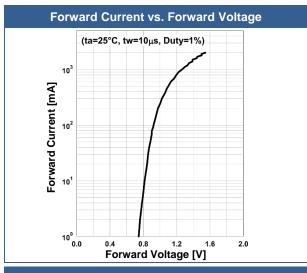
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit	
Peak Wavelength	λ_P	I _F =500mA	1150		1250	nm	
Half Width	$\Delta \lambda$	I _F =500mA		70		nm	
Forward Voltage	VF	I _F =500mA		1.1	1.4	V	
Forward Voltage	V_{FP}	I _{FP} =2A		1.5		V	
Radiated Power *1	Д-	I _F =500mA		50		mW	
Radiated Fower	Po	I _{FP} =2A		130		IIIVV	
Radiant Intensity *2	1_	I _F =500mA		16		mW/sr	
Radiant intensity -	lE	I _{FP} =2A		43		IIIVV/SI	
Viewing Angle	φ	I _F =100mA		136		deg.	
Rise Time	<i>t</i> _R	I _F =500mA		40		ns	
Fall Time	t⊧	I _F =500mA		80		ns	

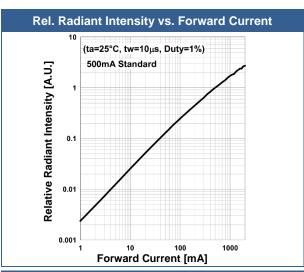
^{*1} measured by G8370-65

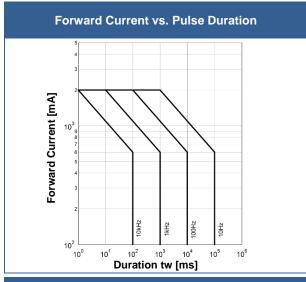
^{*2} must be completed within 5 seconds

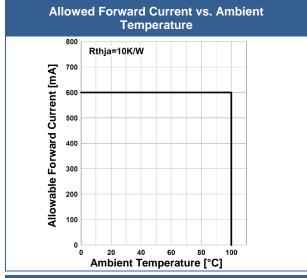
^{*2} measured by ANDO Optical Multi Meter AQ2140 & AQ2743

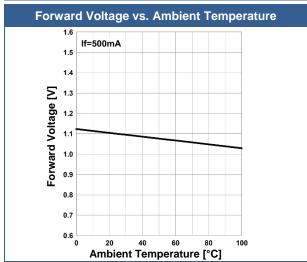
Typical Performance Curves

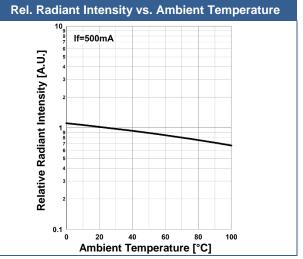










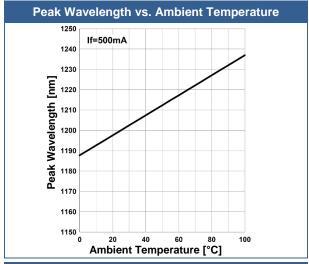


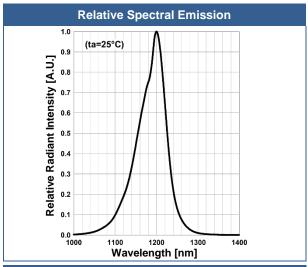


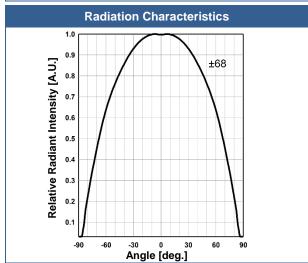
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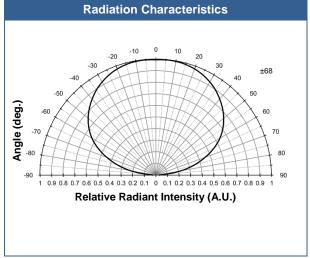
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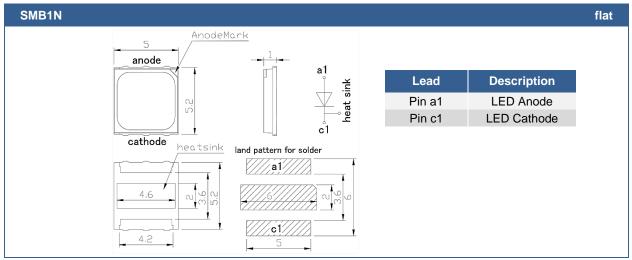








Outline Dimensions



All Dimensions in mm

Precautions

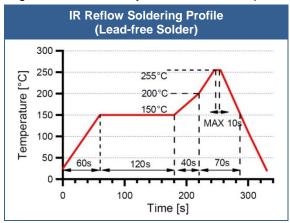
Soldering:

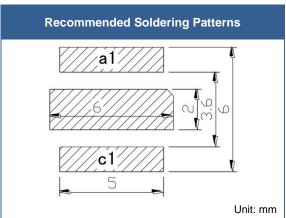
- Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering

Recommended soldering conditions:

This LED is designed to be reflow soldered on to a PCB. If dip soldered or hand soldered, its reliability cannot be guarantee.

Nitrogen reflow soldering is recommended. Air flow soldering conditions can cause optical degradation, caused by heat and/or atmosphere.





Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

Cleaning:

Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroseen, trichloroethylene, or MKS

DO NOT USE ultrasonic cleaners

Static Electricity:

LEDs are sensitive to electrostatic discharge (ESD). Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

Radiation:

During operation these LEDs do emit **high intensity light**, which is hazardous to skin and eyes, and may cause cancer. Do avoid exposure to the emitted light. **Protective glasses are recommended**. It is further advised to attach a warning label on products/systems.

Operation:

Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device. Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.

Revisions History

Rel.	Rel. Date	Chapter	Modification	Page
A2	2021-04	Abstract	50 mW (previously 700 mW)	1
A1	2018-02	-	Initial release	-

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The above specifications are for reference purpose only and subjected to change without prior notice